

# MA3J744 (MA744)

## Silicon epitaxial planar type

For super high speed switching  
For small current rectification

### ■ Features

- High-density mounting is possible
- Forward current (Average)  $I_{F(AV)} = 200$  mA rectification is possible

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

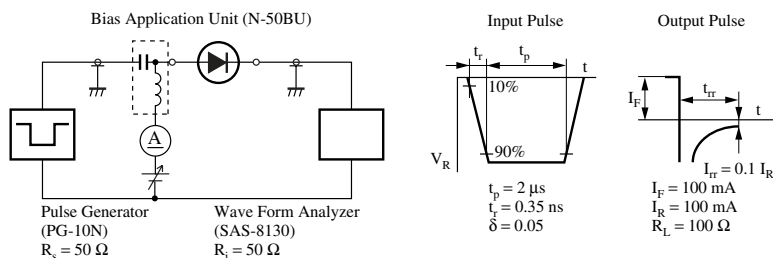
Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	$I_{FM}$	300	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $t = 1$  s

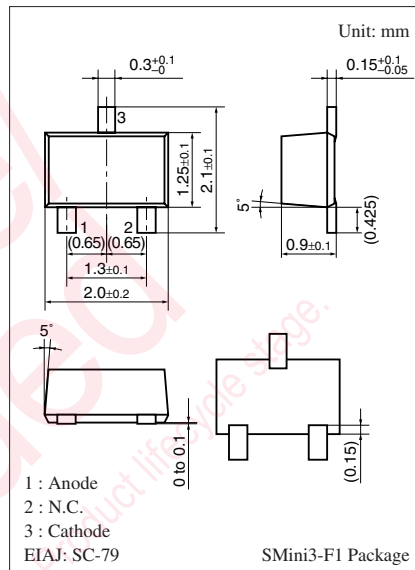
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200$ mA			0.55	V
Reverse current	$I_R$	$V_R = 30$ V			50	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{rr} = 0.1 I_R$ , $R_L = 100 \Omega$		3.0		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.  
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.  
3. Absolute frequency of input and output is 2 GHz.  
4. \*:  $t_{rr}$  measurement circuit

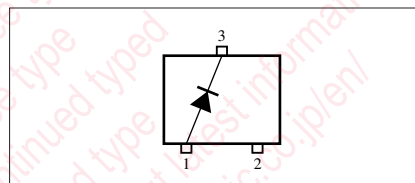


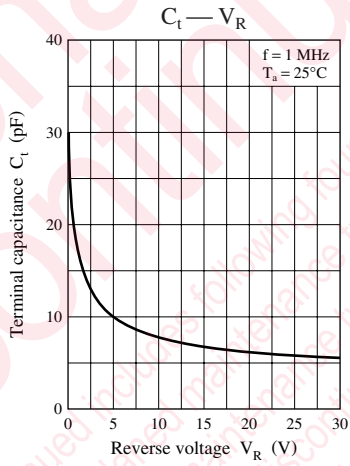
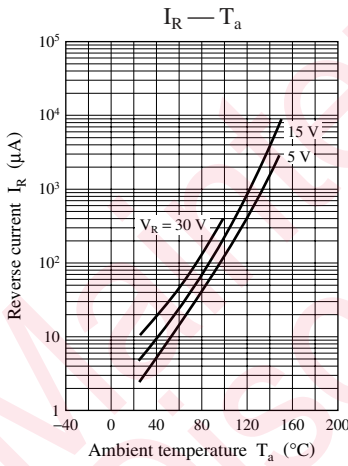
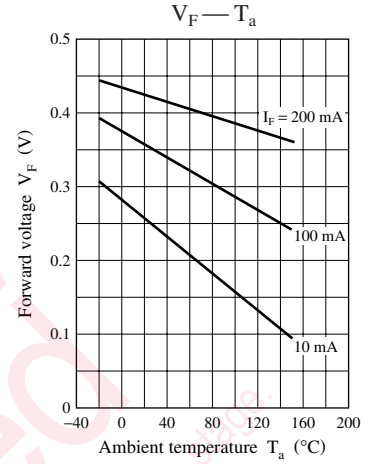
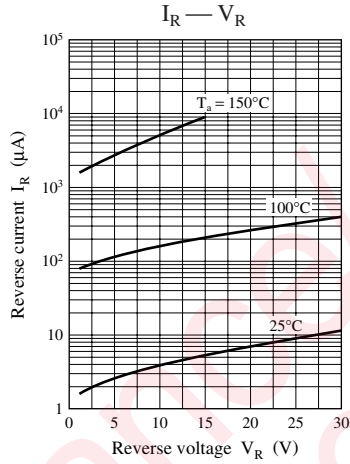
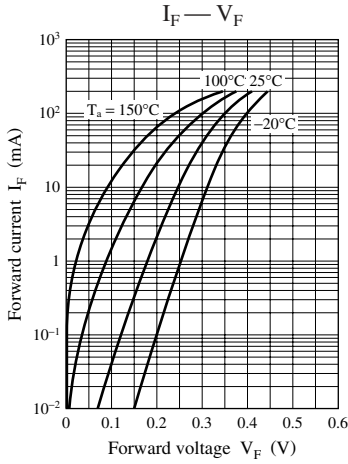
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M1M

Internal Connection





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